



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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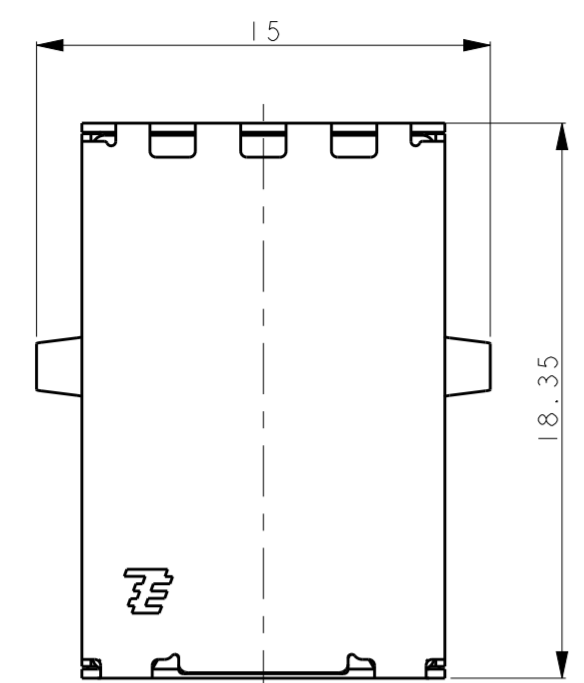
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

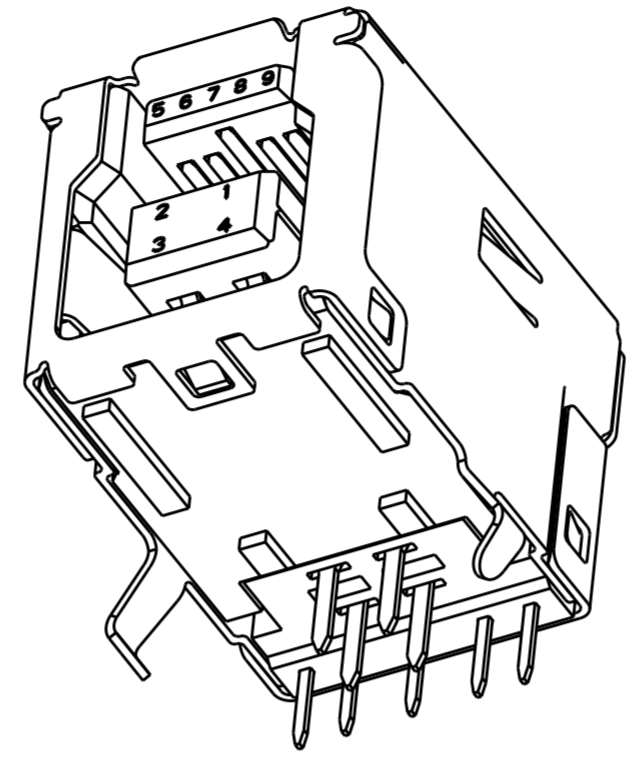


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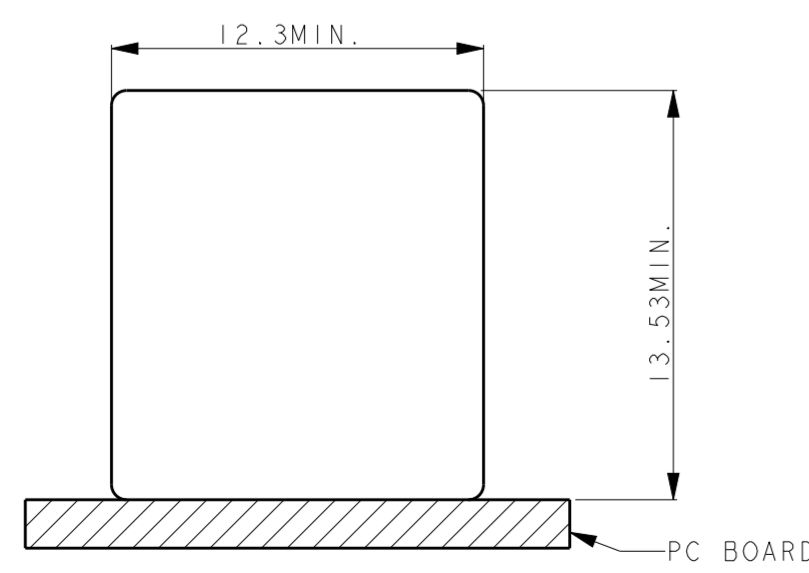
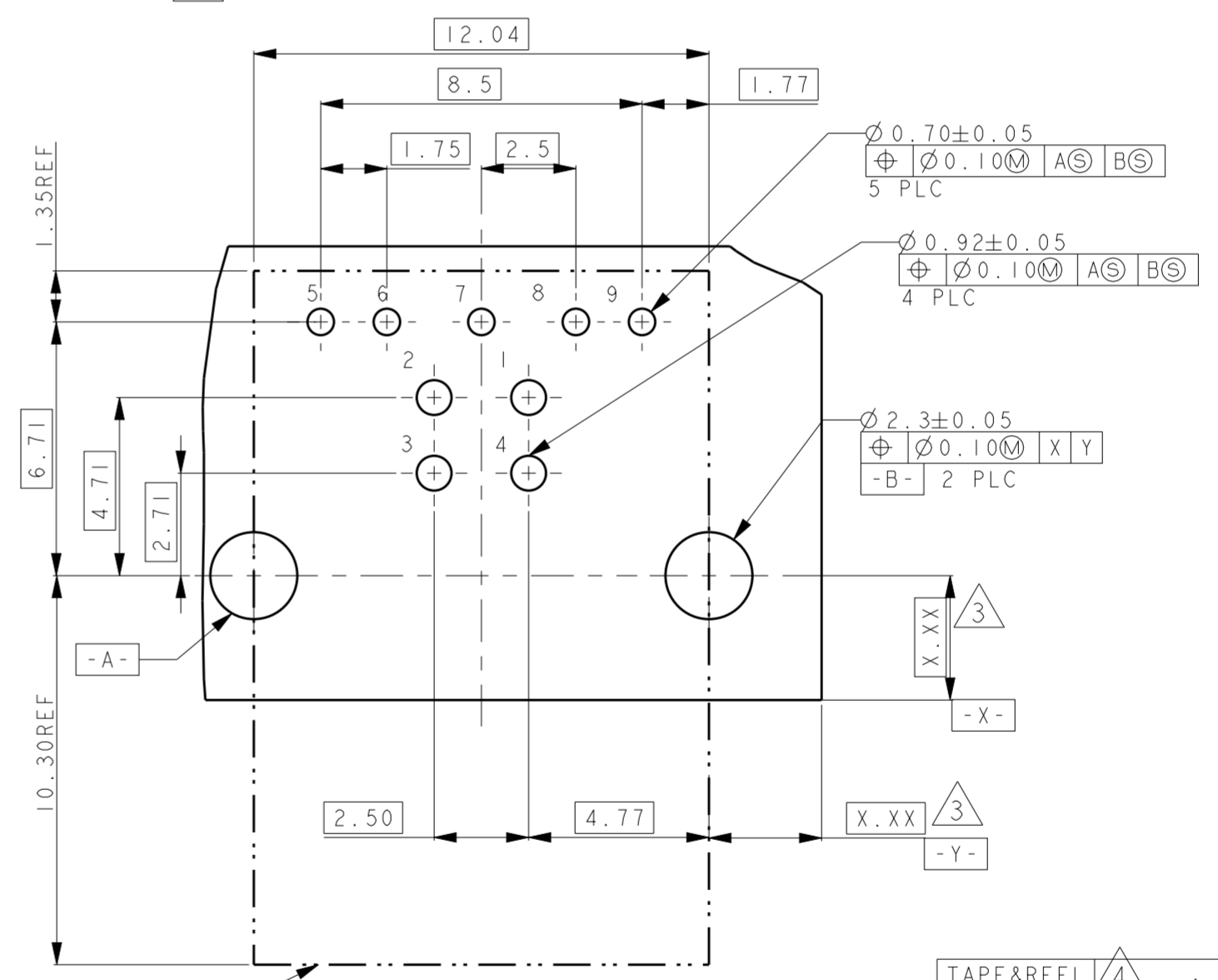
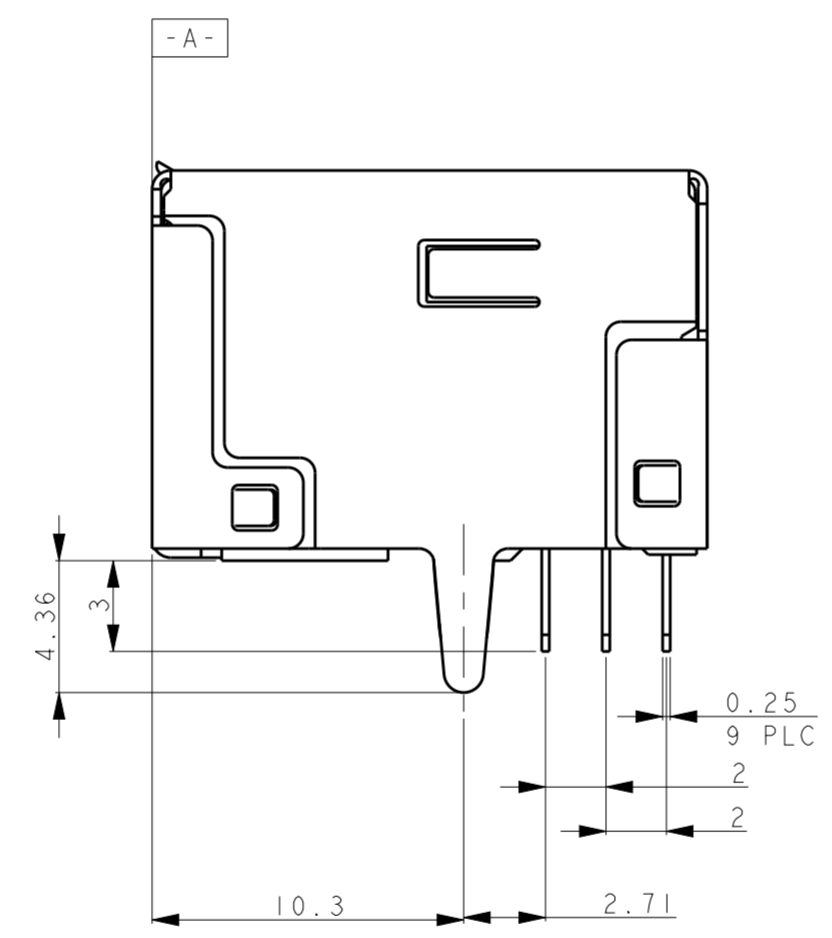
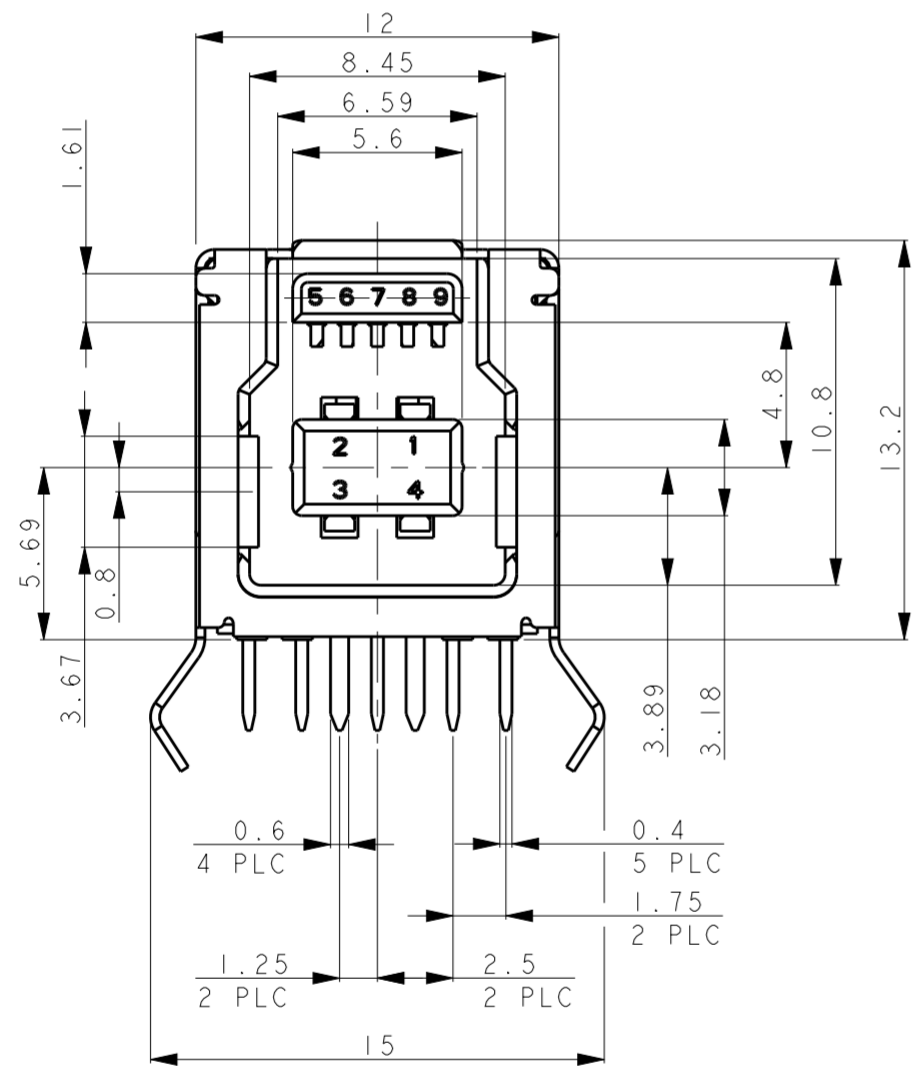
LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
	A	RELEASED PER ECR-12-003396	21FEB2012	F.L	S.Y		
	AI	RELEASED PER ECO-12-017456	29SEP2012	F.L	S.Y		



PIN NO.	SIGNAL NAME	REMARK
1	VBUS	USB 2.0 CONTACT PINS
2	D-	
3	D+	
4	GND	
5	StdB_SSTX-	USB 3.0 CONTACT PINS
6	StdB_SSTX+	
7	GND_DRAIN	
8	StdB_SSRX-	
9	StdB_SSRX+	



- 1 MATERIAL:  
SHELL & CONTACTS: COPPER ALLOY.  
HOUSING & TINE PLATE: THERMOPLASTIC.
- 2 PLATING:  
CONTACT PLATING: 0.76um MIN. GOLD ON MATING AREA.  
2.54um MIN. MATTE TIN ON SOLDER TAILS.  
1.27um MIN. NICKEL UNDER PLATING.  
SHELL PLATING: SOLDERABILITY NICKEL.
- 3 PLATING:  
CONTACT PLATING: 0.38um MIN. GOLD ON MATING AREA.  
2.54um MIN. MATTE TIN ON SOLDER TAILS.  
1.27um MIN. NICKEL UNDER PLATING.  
SHELL PLATING: SOLDERABILITY NICKEL.
- 4 PLATING:  
CONTACT PLATING: GOLDEN FLASH ON MATING AREA.  
2.54um MIN. MATTE TIN ON SOLDER TAILS.  
1.27um MIN. NICKEL UNDER PLATING.  
SHELL PLATING: SOLDERABILITY NICKEL.
- 5 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- 6 RECOMMENDED PC BOARD THICKNESS OF 1.60.



CONNECTOR EDGE LINE FOR REFERENCE  
 RECOMMENDED PCB LAYOUT (CONNECTOR MOUNTING SIDE VIEW) TOP VIEW

PACKAGE	FINISH	MATERIAL	PART NUMBER
TAPE&REEL	4	1	1-1932259-3
TAPE&REEL	3	1	1-1932259-2
TAPE&REEL	2	1	1-1932259-1
TRAY	4	1	1932259-3
TRAY	3	1	1932259-2
TRAY	2	1	1932259-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN FRANCIS LEE 21FEB2012	TE Connectivity NAME USB3.0 STANDARD B TYPE RECEPTACLE SIZE CAGE CODE DRAWING NO RESTRICTED TO A20779 C-1932259 SCALE 4: SHEET OF REV AI
DIMENSIONS: mm		CHK XIANG XU 21FEB2012	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD STEVEN YAO 21FEB2012	
0 PLC ±0.25 1 PLC ±0.25 2 PLC ±0.25 3 PLC ± 4 PLC ± ANGLES ±1° FINISH		PRODUCT SPEC 108-115001 APPLICATION SPEC WEIGHT Customer Drawing	